

LTspice Model

Fast Recovery Rectifier Diode

Diodes

SF24-A5

Model Information

| | |
|-----------------------------------|--|
| Model | A macro model |
| Call Name | MDC_SF24-A5_LT |
| Pin Assign | 1:Port1 2:Port2 |
| File List | Model Library MDC_SF24-A5_LT.lib Model Report MDC_SF24-A5_LT.pdf(this file) |
| Verified Simulator Version | LTspice XVII |
| Note | |

References

The information which was used for modeling is as follow:

[Data Sheet]

| | |
|---------------|---------------------|
| ●Date/Version | Version: L2102 |
| ●Product name | SF24-A5 |
| ●Company name | Diodes Incorporated |

[Characteristics listed]

| | |
|------------------|--|
| ●Characteristics | Reverse Current – Reverse Voltage Forward Current – Forward Voltage Junction Capacitor – Reverse Voltage |
|------------------|--|

Simulation Condition

This table shows the range of evaluated simulation range that was not occurs any convergence problems in this area.

| Item | Condition | Unit |
|-------------|------------|-------|
| Temperature | 25,100,150 | deg C |

○ : Implemented
 × : Not Implemented
 — : Not applicable

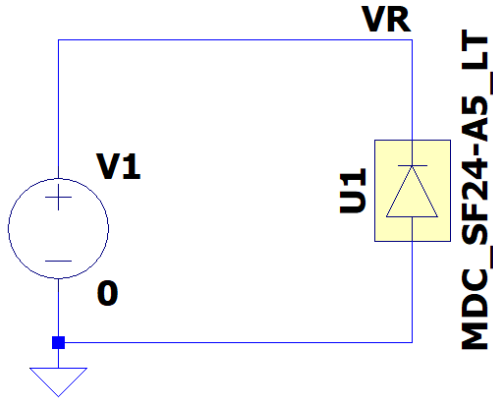
Model Functions Table
RANK=1

| Functions | RANK | Implemented |
|---------------------------------------|------|-------------|
| IF-VF | 1 | ○ |
| IR-VR(Temp) | 1 | ○ |
| Capacitance | 1 | ○ |
| Reverse recovery characteristics | 1 | — |
| Rectification characteristics(Bridge) | 1 | — |
| Surge voltage-Transient | 2 | — |

Reverse Current – Reverse Voltage

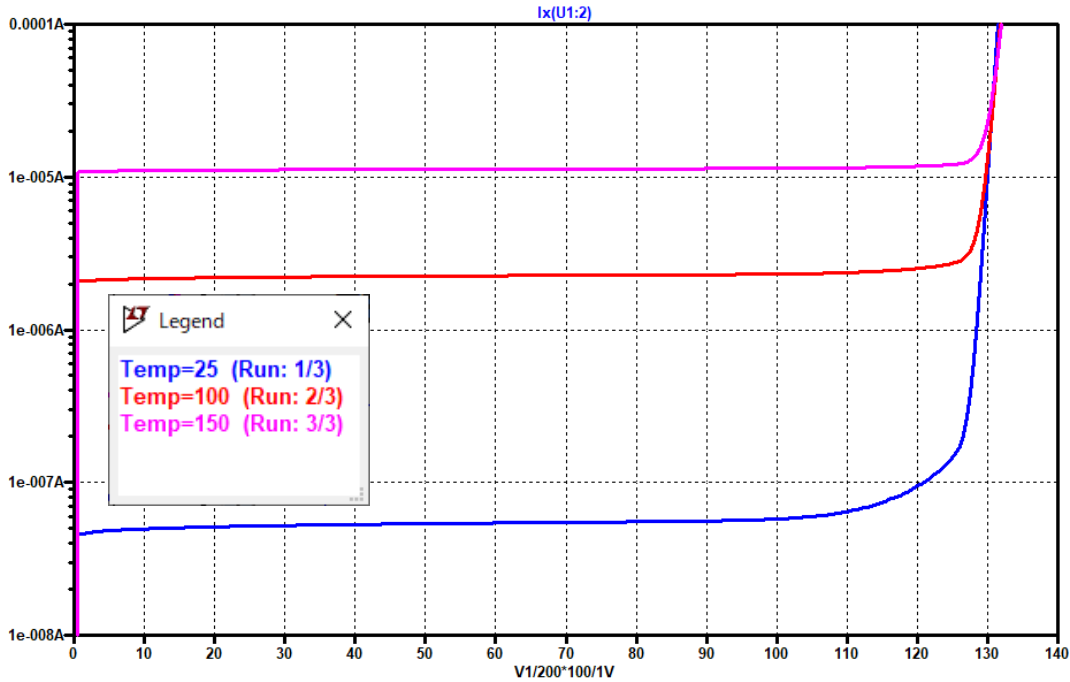
TestBench

```
.dc V1 0 280 1
.OPTION TNOM=25 GMIN=1e-15
.TEMP 25 100 150
```



Simulation results are following.

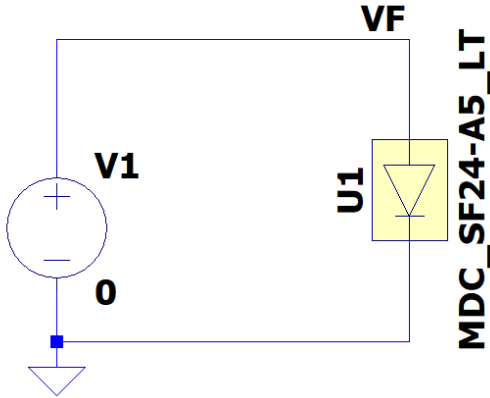
Explanatory notes — : simulated



Forward Current – Forward Voltage

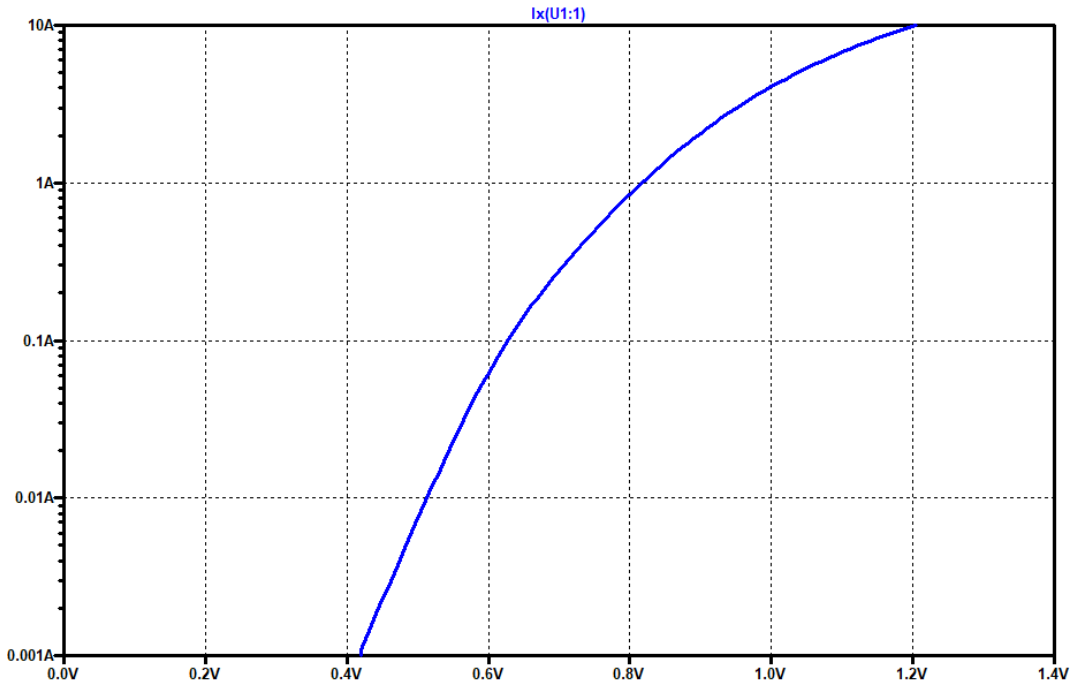
TestBench

```
.dc V1 0 1.4 0.01
.OPTION TNOM=25 GMIN=1e-15
.TEMP 25
```



Simulation results are following.

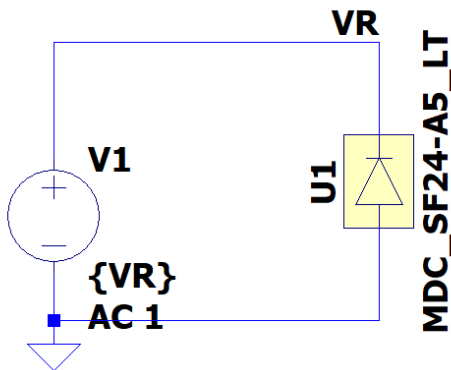
Explanatory notes — : simulated



Junction Capacitor – Reverse Voltage

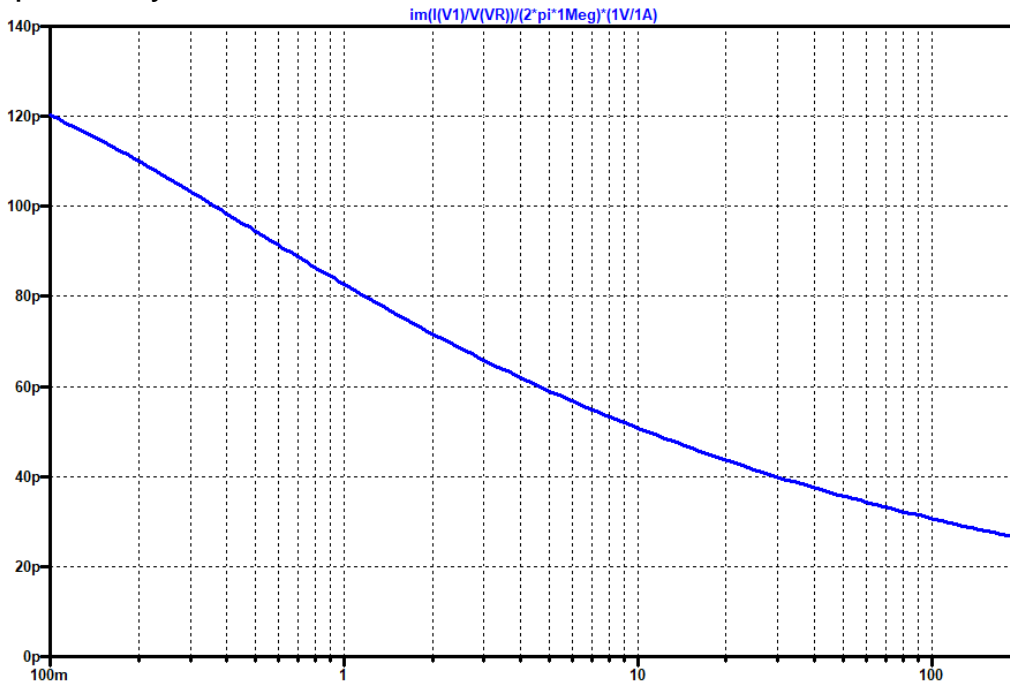
TestBench

```
.step dec param VR 0.1 200 10
.ac lin 1 1Meg 1Meg
.OPTION TNOM=25 GMIN=1e-15
.TEMP 25
```



Simulation results are following.

Explanatory notes — : simulated



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